

M1 cut
 area between the main surface of the semiconductor chip and the main surface of the resin seal member.

IN THE CLAIMS

Rewrite claim 7 and add new claim 8 as follows:

A2
 7. (Amended) A semiconductor device according to claim 4, wherein the main surface of the semiconductor chip is formed in a rectangular shape in which the first and second sides of the main surface of the semiconductor chip are a long side and a short side, respectively.

A3
 8. (New) A semiconductor device according to claim 4, wherein the main surface of the semiconductor chip is formed in a rectangular shape in which the first and second sides of the main surface of the semiconductor chip are a short side and a long side, respectively.

REMARKS

Claim 7 has been amended to correct an inadvertent error, and claim 8 was unintentionally omitted from the application and has been added.

Examination is requested.

Respectfully submitted,

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